MA2SD310G

Silicon epitaxial planar type

For super high speed switching

■ Features

- $I_{F(AV)} = 200$ mA rectification is possible.
- Low forward voltage: $V_F < 0.47 \text{ V}$ (at $I_F = 200 \text{ mA}$)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V _{RRM}	30	V
Forward current (Average)	I _{F(AV)}	200	mA
Peak forward current	I_{FM}	300	mA
Non-repetitive peak forward surge current *	I _{FSM}	1	A
Junction temperature	T _j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

Package

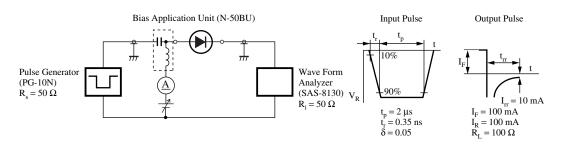
- Code
- SSMini2-F4
- Pin Name
 - 1: Anode 2: Cathode

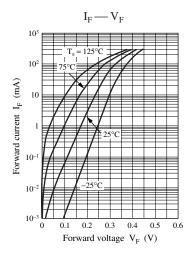
■ Marking Symbol: 8F

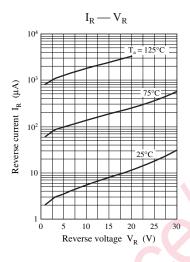
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

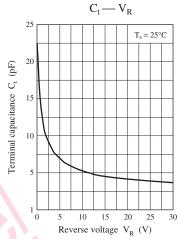
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 200 \text{ mA}$		0.38	0.47	V
Reverse current	I_{R1}	$V_R = 10 \text{ V}$			20	μΑ
	I_{R2}	$V_R = 30 \text{ V}$			200	
Terminal capacitance	C_{t}	$V_R = 0 V, f = 1 MHz$		25		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		2		ns
	W _C	$I_{rr} = 10 \text{ mA}, R_{L} = 100 \Omega$				

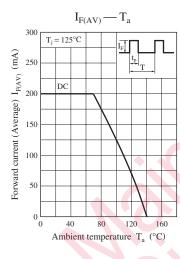
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 250 MHz
 - 4. *: t_{rr} measurement circuit







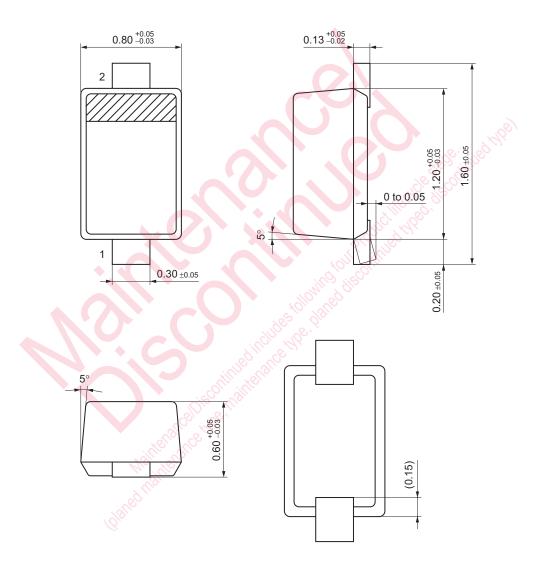




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SKH00182BED

SSMini2-F4 Unit: mm



SKH00182BED 3

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